



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



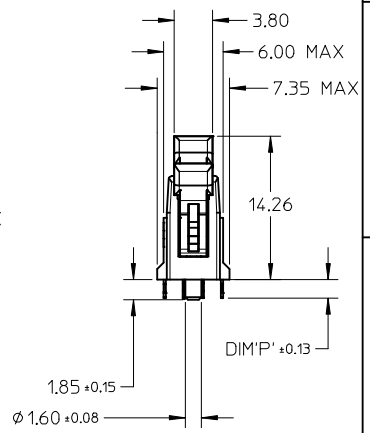
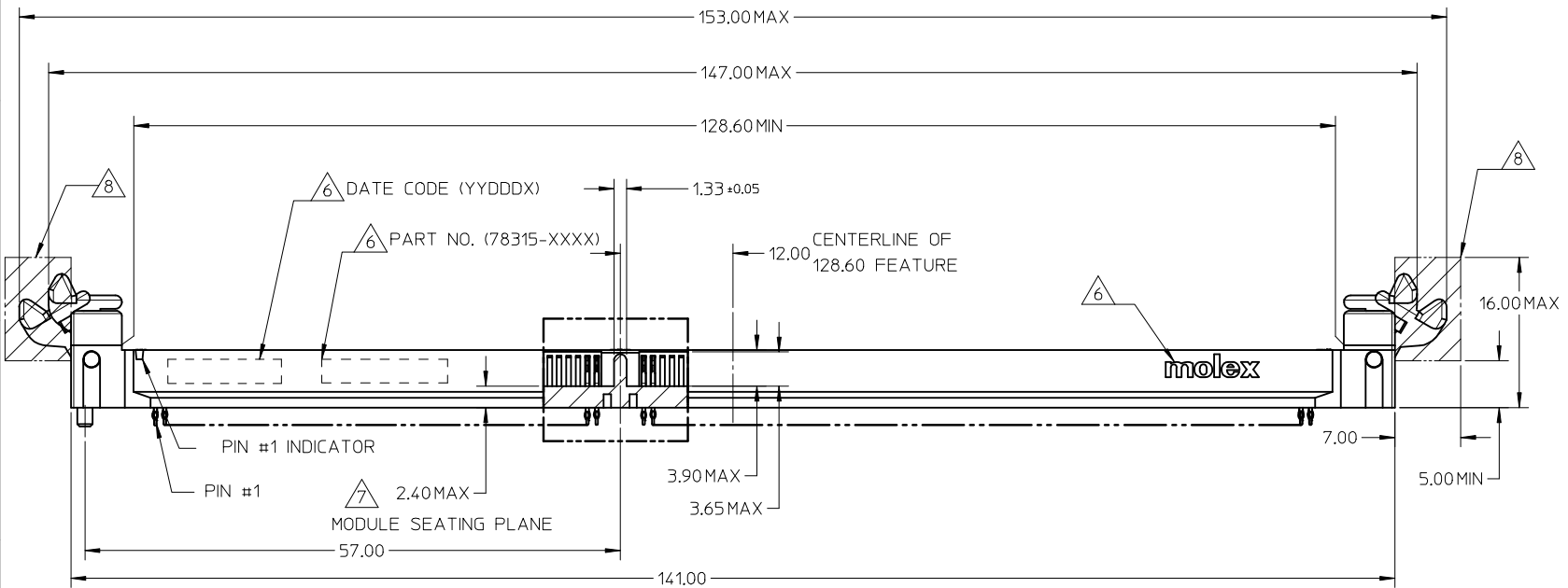
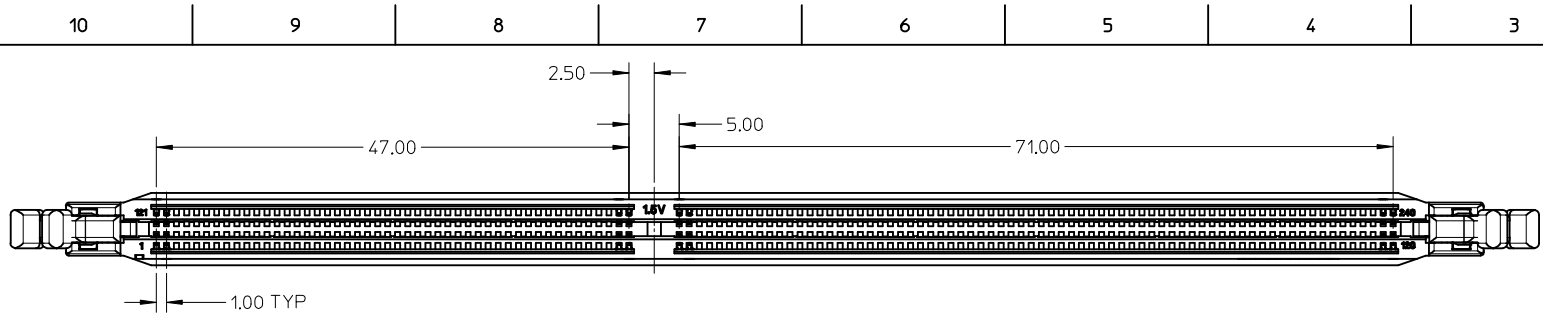
## Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





- NOTES:
- MATERIAL:  
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK  
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK  
TERMINAL - COPPER ALLOY
  - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
  - PRODUCT SPECIFICATION: PS-78315-001
  - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
  - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
  - MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING  
DATE CODE SHOULD BE INDICATE AS YYDDDX. 'X' WILL BE THE DIE NO.
  - MODULE SEATING PLANE FROM TOP OF PCB
  - KEEP OUT ZONE RESERVED FOR LATCH

UPT D/C W DIE NO	2015/01/20
EC NO: S2016-1099	2016/07/19
DRW:NCCTEH	2016/07/19
CHKD:CGTAN	2016/07/19
APPR:SHLENI	2016/07/19

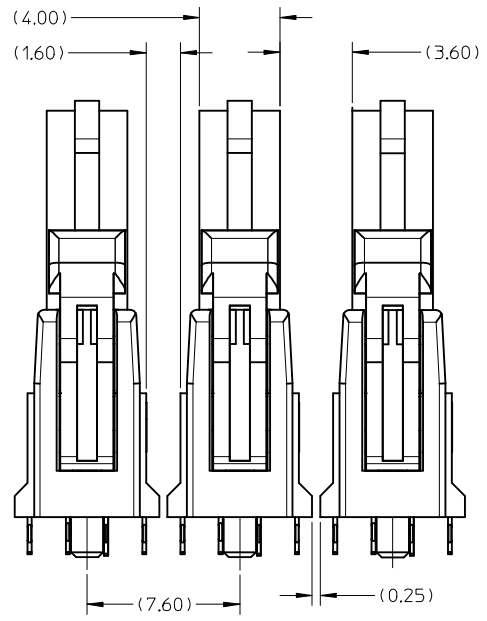
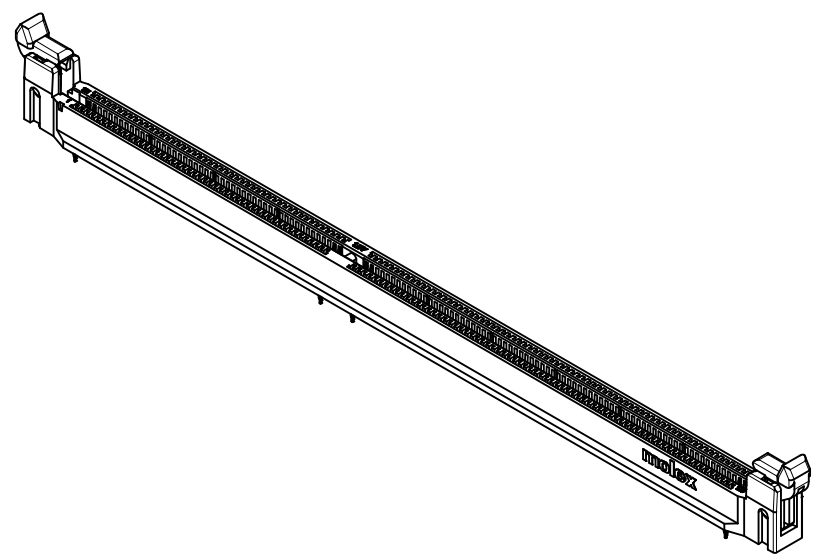
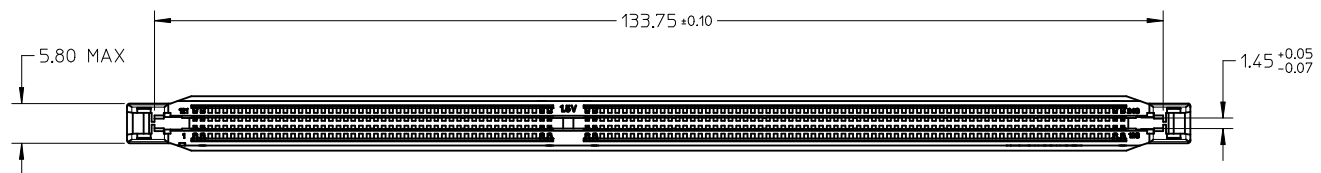
QUALITY SYMBOLS	DESCRIPTION
$F_A=0$	
$F_G=0$	
$F_B=0$	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.20 ± ---
1 PLACE	± --- ± ---
0 PLACE	± --- ± ---
ANGULAR ± 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
CMTEO	2008/07/17
CHECKED BY	DATE
CCTEH	2008/07/30
APPROVED BY	DATE
SHLENI	2010/12/15
MATERIAL NO.	
SEE TABLE	

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
DDR3 DIMM (LSP, VLP) 100MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
<b>molex</b>		
DOCUMENT NO.	SHEET NO.	
SD-78315-001	1 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



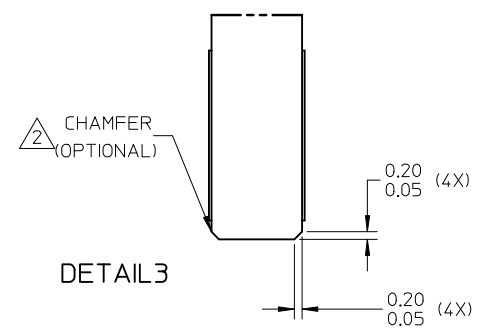
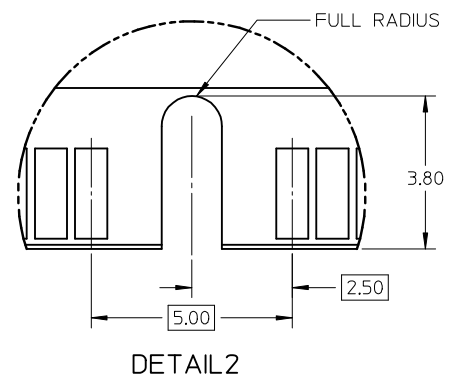
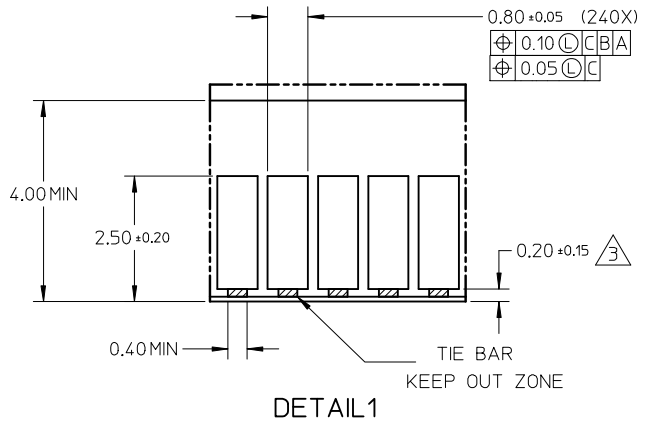
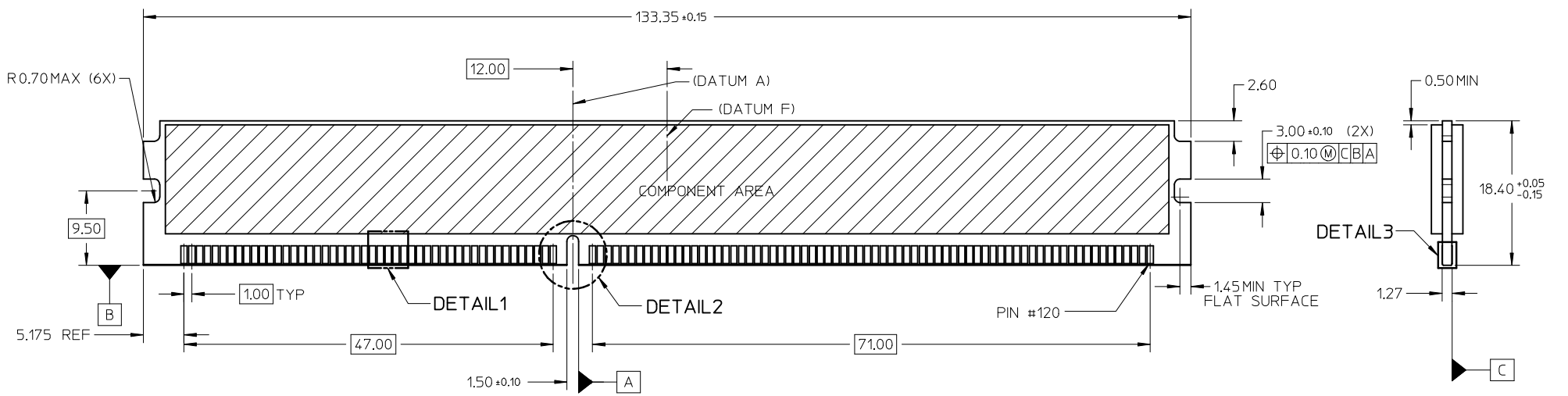
MINIMUM ROW TO ROW SPACING RECOMMENDATION  
(USING 4.00MM MODULE CARD)

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_s = 0$ $F_G = 0$ $F_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR  <b>molex</b> DOCUMENT NO. SD-78315-001 SHEET NO. 2 OF 6			
		3 PLACES	± ---	± ---	CHECKED BY	DATE				
2 PLACES	± 0.20	± ---	CCTEH	2008/07/30						
1 PLACE	± ---	± ---	APPROVED BY	DATE						
0 PLACE	± ---	± ---	SHLENI	2010/12/15	MATERIAL NO.		SEE TABLE			
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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10 9 8 7 6 5 4 3 2 1

009MODULE CARD  
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS  
 (JEDEC MO-269, ISSUE A, 12/05)



NOTES:

1. RECOMMENDED PLATING FOR CONTACT PADS:  
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN  
 OVER 2.00 MICROMETERS NICKEL  
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING  
 OVER 2.00 MICROMETERS NICKEL MUST  
 USE AN ELECTRONIC CONTACT GRADE  
 CORROSIVE BARRIER LUBRICANT

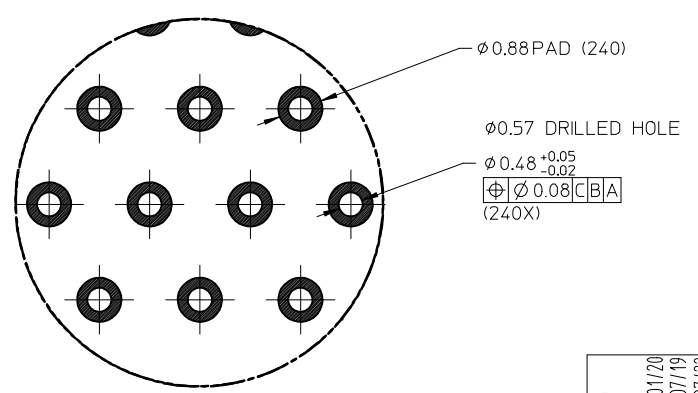
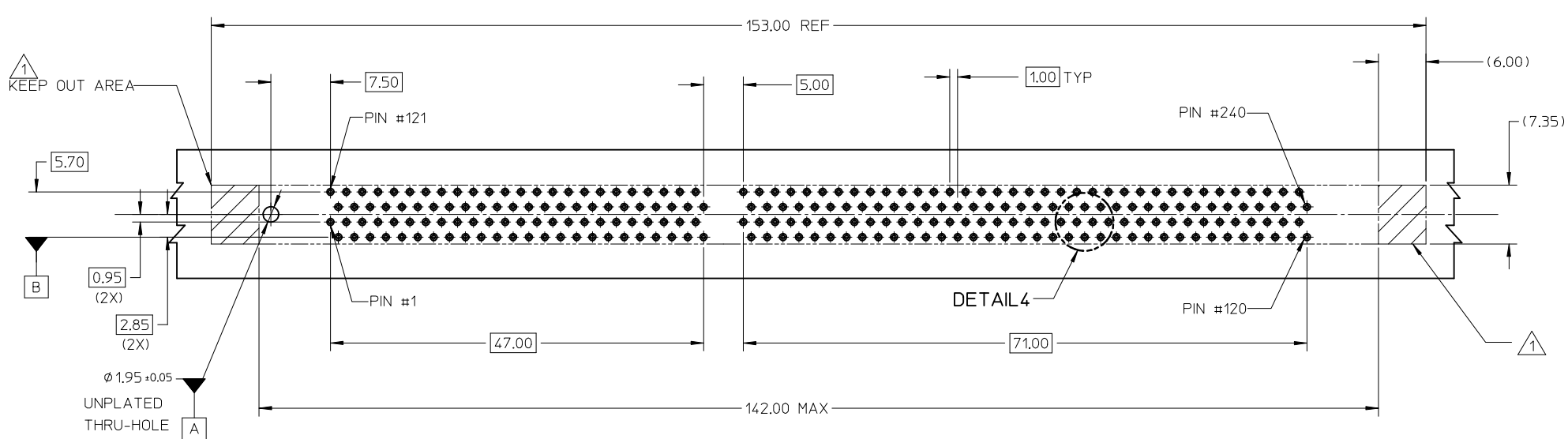
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS

3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE  
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

UPT D/C W DIE NO A3	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
						MM ONLY		NTS	METRIC		
					mm	INCH	DRAWN BY	DATE	TITLE		
				4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)		
					1.00MM PITCH, 240 CKTS						
							VERTICAL P/F, LOWLLCR				
							molex				
							SD-78315-001				
							3 OF 6				
							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



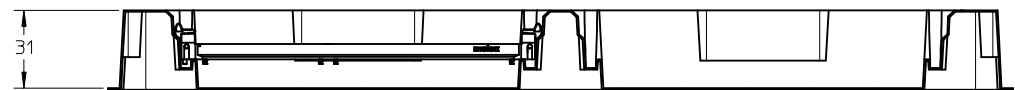
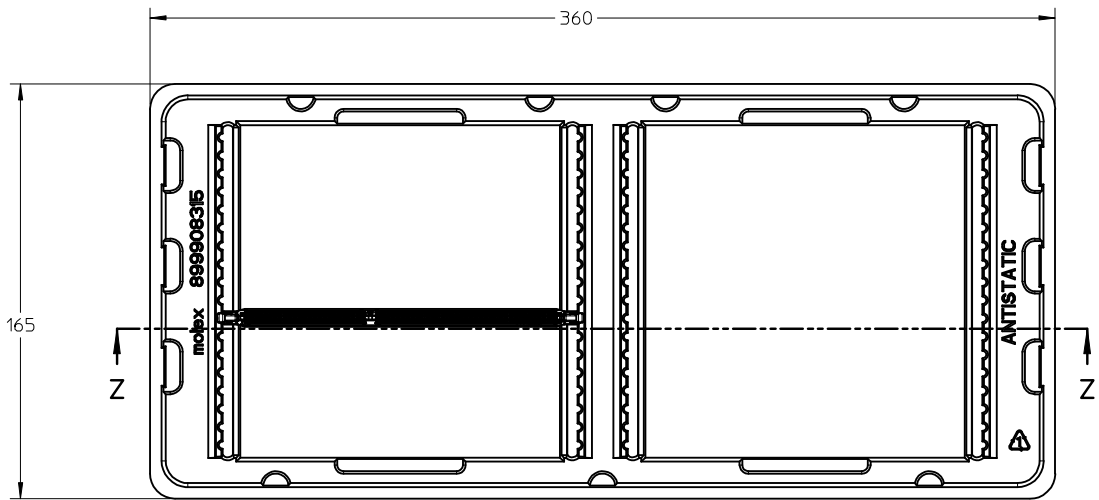
NOTES:  
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHYK: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
		4 PLACES 3 PLACES 2 PLACES 1 PLACE 0 PLACE	$\pm$ --- $\pm$ --- $\pm$ 0.20 $\pm$ --- $\pm$ ---	$\pm$ --- $\pm$ --- $\pm$ --- $\pm$ --- $\pm$ ---	CHECKED BY CCTEH	DATE 2008/07/30	APPROVED BY SHLENI	DATE 2010/12/15	MATERIAL NO. SEE TABLE
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR $\pm 1^\circ$	DOCUMENT NO. SD-78315-001		SHEET NO. 4 OF 6		

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

NOTE:  
1. NO. OF CAVITY - 18 X 2 =36

UPT D/C W DIE NO EC NO: S2016-1099 DRW: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22	QUALITY SYMBOLS $\nabla_{\text{A}}=0$ $\nabla_{\text{G}}=0$ $\nabla_{\text{F}}=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	CHECKED BY CCTEH	DATE 2008/07/30	APPROVED BY SHLENI			
		0 PLACE ± --- ± ---	ANGULAR ± 1 °	MATERIAL NO. SEE TABLE	DATE 2010/12/15	DOCUMENT NO. SD-78315-001	SHEET NO. 5 OF 6		
A3	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION		LATCH COLOUR	HOUSING COLOUR
				CONTACT AREA	TAIL AREA		
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78315-0051						BLUE	BLUE
78315-0011		2.85	2.60			BLACK	BLACK

UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	4 PLACES	mm	INCH	DRAWN BY	DATE	TITLE		
	$F_G=0$	3 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
	$F_P=0$	2 PLACES	± 0.20	± ---	CCTEH	2008/07/30	<b>molex</b>		
	1 PLACE	± ---	± ---	APPROVED BY	DATE	DOCUMENT NO.			
	0 PLACE	± ---	± ---	SHLENI	2010/12/15	SD-78315-001		6 OF 6	
		ANGULAR ± 1 °		MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE					
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1